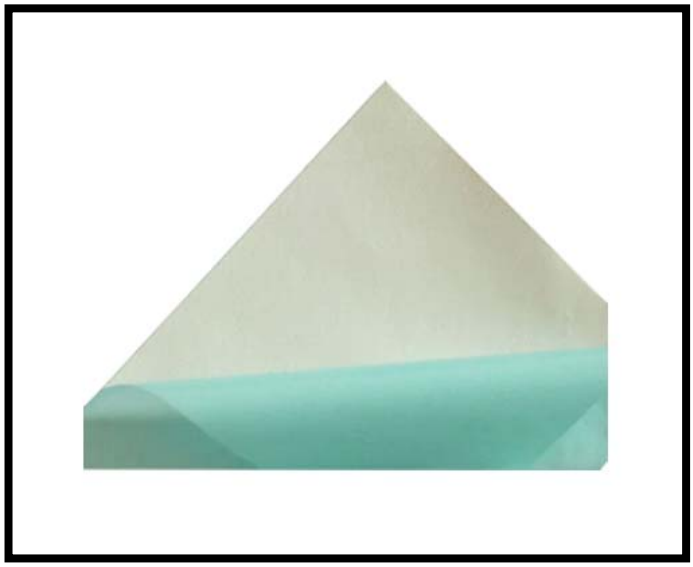
Thermal Management Materials, 6019 Material

Product Summary

MAJR 6000 Series thermal Management materials consist of sheet, adhesive, grease compounds and tape; these thermal materials are used in a wide variety of markets such as LED, chip sets for IC controller packages, IT for industrial and personal computers, DRAM Modules, telecom devices, automotive control units, and many other products for military and commercial markets.

Product Application (6019)

This family of thermally conductive tapes exhibit excellent adhesion capabilities at 1.1 to 1.4 kg/inch with a thermal conductivity of 1.2W/m-k. In addition, these materials exhibits a continuous use temperature of -20 to 120 deg. C. they are excellent for applications such as: DDR RAM assembly, and LED lighting. The material can be supplied in sheet, roll form, and die-cut parts to your specification. Standard thickness is: 0.05mm, 0.10mm, 0.20mm. Max. width is 1030mm.



Product Technical Data (6019)

Physical

Properties	T1	T2	T3	T4
Properties	8N12-T05	8N12-T10	8N12-T15	8N12-T20
Carrier	NONE	NONE	NONE	NONE
Thickness	0.05mm	0.10mm	0.15mm	0.20mm

Adhesion

Peel Strength (PSTC-101)(N/25mm)	>10.78	>13.72	>13.72	>15.68
Temp Resistance(S) °C (°F)	180（356）	180（356）	180（356）	180（356）
Temp Resistance(L) °C(°F)	120（248）	120（248）	120（248）	120（248）

Technical Data (6019) continued

Adhesion continued

Continues Use. Temp. (°C)	-20 to 120	-20 to 120	-20 to 120	-20 to 120
Retention （1Kg/Inch/25°C)	>48	>48	>48	>48
Adhesion(Kg/Inch)	1.1	1.4	1.4	1.4
Initial Adhesion(J.DOW)	8	12	14	16

Electrical

Breakdown Voltage(Kv)	1.57	2.22	2.55	4.29

Thermal

Thermal conductivity (ASTM D5470)	1.2w/m.k	1.2w/m.k	1.2w/m.k	1.2w/m.k
Thermal Resistance (AMD 2240)@40PSI	0.414C*in^2/w	0.558C*in^2/w	1.07C*in^2/w	1.173C*in^2/w

Shelf life: 15 months at a maximum storage temperature of 28 deg. C, relative humidity of 60%.